



An Introduction to Electronics Systems Packaging

Video Course -2012

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Quiz for Module 1

Overview of electronics systems packaging

Video Sequence 1-5

1. Define a microsystem. What application areas does it encompass?
 2. What are the three basic levels of electronic systems packaging?
 3. If you look at the history of the growth of micro-processors, what are the two striking observations you can make which highlights high density interconnect packaging?
 4. Define Moore's Law. Is this law valid in today's context of semiconductor growth?
 5. From the ITRS roadmap for semiconductors, discuss how thermal management of the devices can be resolved by technological advances (materials and processes)?
 6. What are the crucial challenges for the packaging industry observed from the ITRS and other roadmaps for packaging?
 7. Why does packaging considerations become challenging for automotive electronics industry? How do you trade-off cost and reliability issues here?
 8. Explain 'system' and 'system functions'. Give an example for a system function.
 9. Define electronics packaging. What are the major functions of electronics packaging?
 10. Discuss more detailed structures of levels of packaging.
 11. What is the packaging level at which a printed circuit board would fit in?
 12. Briefly write about system integration in a desktop computer with current technology standards and components.
 13. What is a PWB? What is the purpose of a PWB?
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